Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

### SSM6N25TU

#### **High Speed Switching Applications**

• Optimum for high-density mounting in small packages

• Low on-resistance:  $R_{on} = 395 \text{m}\Omega \text{ (max) (@V_{GS} = 1.8 V)}$ 

 $R_{on} = 190 \text{m}\Omega \text{ (max) } (@V_{GS} = 2.5 \text{ V})$ 

 $R_{on} = 145 m\Omega \text{ (max) } (@V_{GS} = 4.0 \text{ V})$ 

## Absolute Maximum Ratings (Ta = 25°C) (Q1, Q2 Common)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		$V_{DS}$	20	V	
Gate-Source voltage		V <sub>GSS</sub>	± 12	V	
Drain current	DC	I <sub>D</sub>	0.5	А	
	Pulse	I <sub>DP</sub>	1.5		
Drain power dissipation		P <sub>D</sub> (Note 1)	500	mW	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the

Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

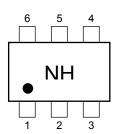
Note 1: Mounted on FR4 board. (total dissipation) (25.4 mm  $\times$  25.4 mm  $\times$  1.6 t, Cu Pad: 645 mm<sup>2</sup> )

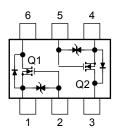
# 2.1±0.1 1.7±0.1 1.7±0.1 1.0±0.1 1.0±0.1 2.000-5.0 4 9000-91.0 1.Source1 4.Source2 2.Gate1 5.Gate2 3.Drain2 6.Drain1

Weight: 7.0 mg (typ.)

#### Marking

#### **Equivalent Circuit (top view)**





#### **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

#### Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

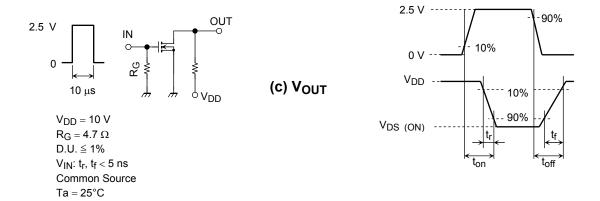
Charact	teristics	Symbol	Test Condition		Min	Тур.	Max	Unit	
Gate leakage curr	ent	I <sub>GSS</sub>	$V_{GS} = \pm 12V, V_{DS} = 0$		_		±1	μА	
Drain-Source breakdown voltage	V (BR) DSS	$I_D = 1 \text{ mA}, V_{GS} = 0$		20	_	_	V		
	V (BR) DSX	$I_D = 1 \text{ mA}, V_{GS} = -12 \text{ V}$		10	_	_	V		
Drain cut-off curre	nt	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0		_	_	1	μА	
Gate threshold vo	Itage	V <sub>th</sub>	$V_{DS} = 3 \text{ V}, I_{D} = 0.1 \text{ mA}$		0.5	_	1.1	V	
Forward transfer a	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 3 V, I <sub>D</sub> = 0.25 A	(Note2)	1.2	2.4	_	S	
Drain-Source on-resistance		R <sub>DS</sub> (ON)	I <sub>D</sub> = 0.25 A, V <sub>GS</sub> = 4.0 V	(Note2)	_	125	145	mΩ	
			I <sub>D</sub> = 0.25 A, V <sub>GS</sub> = 2.5 V	(Note2)	_	150	190		
			$I_D = 0.25 \text{ A}, V_{GS} = 1.8 \text{ V}$	(Note2)	_	200	395		
Input capacitance		C <sub>iss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		_	268	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz		_	34	_	pF	
Output capacitance		C <sub>oss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz		_	44	_	pF	
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 10 \text{ V}, I_D = 0.25 \text{ A},$		_	11	_	— ns	
	Turn-off time	t <sub>off</sub>	$V_{GS} = 0 \sim 2.5 \text{ V}, R_G = 4.7 \Omega$		_	15	_		

Note2: Pulse test

#### **Switching Time Test Circuit**

(a) Test Circuit

(b) V<sub>IN</sub>

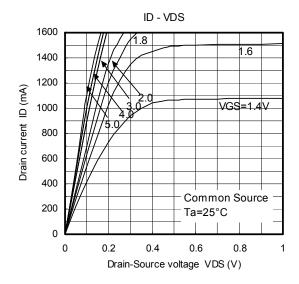


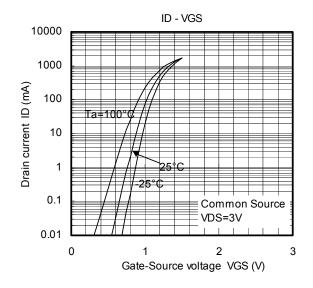
#### **Precaution**

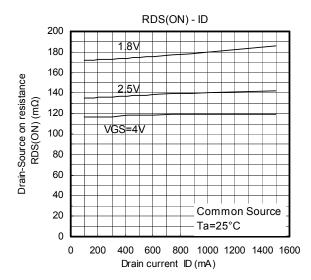
 $V_{th}$  can be expressed as the voltage between gate and source when the low operating current value is  $I_D$ =100  $\mu A$  for this product. For normal switching operation,  $V_{GS}$  (on) requires a higher voltage than  $V_{th}$  and  $V_{GS}$  (off) requires a lower voltage than  $V_{th}$ .

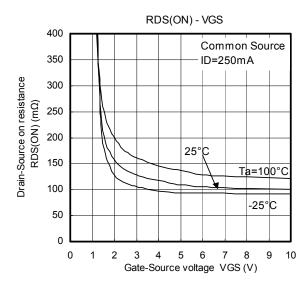
(The relationship can be established as follows:  $V_{GS (off)} < V_{th} < V_{GS (on)}$ )

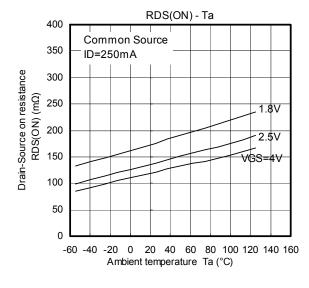
Please take this into consideration when using the device.

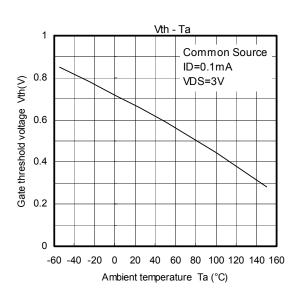


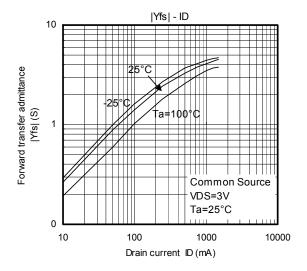


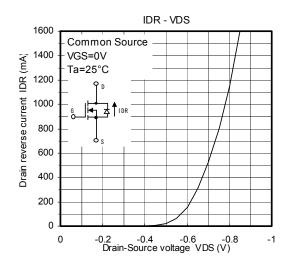


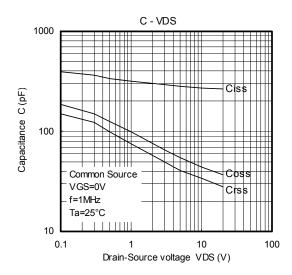


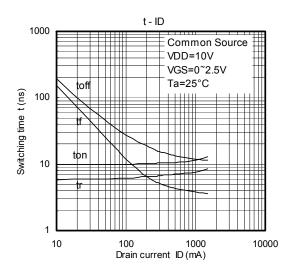


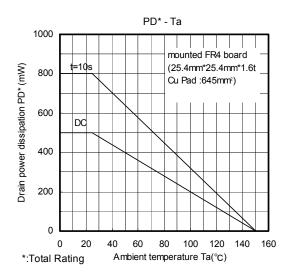


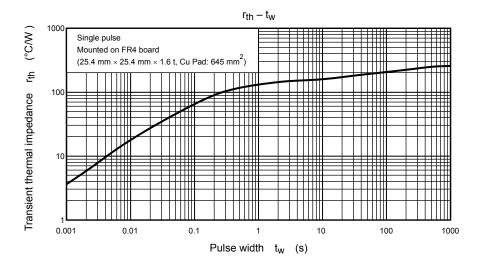












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20070701-EN GENERAL

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